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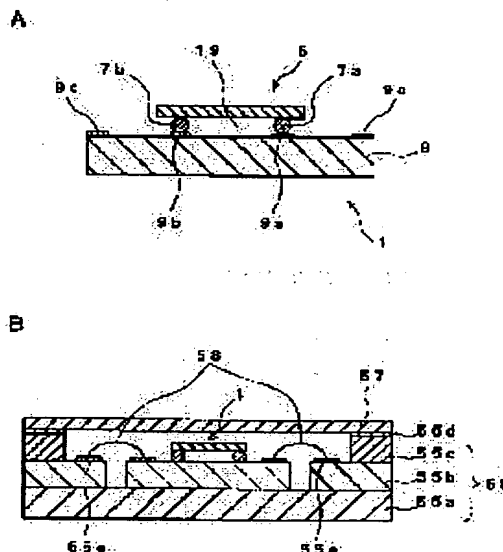
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(54) DEVICE HAVING SURFACE ACOUSTIC WAVE ELEMENT AND ITS MANUFACTURE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide the surface acoustic wave element to be miniaturized with high reliability.

SOLUTION: A SAW chip 5 is mounted above an LSI 9 via bumps 7a, 7b. Input output electrodes and external connection electrodes 9a, 9b are connected electrically by the bumps 7a, 7b. The SAW chip and the LSI 1 once manufactured separately are structured to be a 2-stage stack structure, then miniaturization is attained without the use of a piezoelectric thin film forming technology. Moreover, no bonding wire is required between the SAW chip and the LSI 1 by using the bumps.



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